TEXAS INSTRUMENTS

TI DESIGNS

Bill of Materials

PMP7672 BOM

Qty	Value	RefDes	Part Number	Manufacturer	Description	Size
2	0.1uF/X2	C1 C2	B32922C3104M	Epcos	CAP FILM 0.1UF 630VDC RADIAL	18mm x 5mm x 10.5mm
1	220uF/63V	C10	EEU-FC1J221	Panasonic	CAP ALUM 220UF 63V 20% RADIAL,105DegC	12.5mm(dia.)x 22mm (height)
1	330uF/63V	C11	EEU-FC1J331	Panasonic	CAP ALUM 330UF 63V 20% RADIAL,105DegC	12.5mm(dia.)x20mm (height)
1	1uF/100v	C12	Std	Std	CAP CER 1UF 100V 20% X7R 1206	1206
1	DNP	C13	BFC233820104	Vishay	CAP FILM 0.1UF 630VDC RADIAL	Leaded, Size<12mm(L)X6mm(W)x12mm(H), Pin distance: 10mm
1	0.047uF/310VAC	C3	BFC233820473	Vishay	CAP FILM 0.047UF 630VDC RADIAL	Leaded, Size<10mm(L)X5mm(W)x10.5mm(H), Pin distance: 7.5mm
1	3.3nF/630v	C4	FK26X7R2J332K	TDK	Capacitor, Ceramic, 630V, X7R,+/-10%	Leaded, Size<5.5mm(L)X3.5mm(W) x6mm(H), Pin distance: 5mm
1	DNP	C5	STD	STD	Capacitor, 100pF Ceramic Chip, 50V, ±10%	805
1	10uF/35V	C6	Std	Std	CAP ALUM 10uF 35V 20% RADIAL	5mm(dia.)x7mm (height). Lead spacing 2.5mm
1	10pF	C7	Std	Std	CAP CER 22pF 16V 10% X7R 0805	805
1	6.8uF/16V	C8	Std	Std	CAP CER 6.8uF 16V 10% X7R 0805	805
1	2200pF/Y1	C9	Std	Std	Y1 CAP, 2200pF, 250VAC, -25to105DegC,	Lead space, 10mm, 11.5mm Dia

1	DNP	C14	Std	Std	Capacitor, 0.1uFCeramic Chip, 50V, ±10%	805
1	1A/600V	D1	DF06S-T	Diodes Inc	Bridge Rectifier, 600V, 1A	DFS-4 Pin SMD Gullwing
1	0.2A, 200V	D2	BAS20LT1G	ON Semiconductor	DIODE SWITCHING 200V 200MA SOT23	SOT-23-3
1	1A, 1000V	D3	US1M-E3/61T	Vishay	Diode Ultrafast Rectifier, 1A, 1000V	SMA
1	SD101CW	D4	BAT54FILM	ST Micro	Diode, Schottky, 300mA, 40V	SOT-23-3
1	3A,400V	D5	ES3G-E3/57T	Vishay	Diode,ultra fast, 3A/400V	SMC
1	DNP	D6	1N4007	Std	Diode, General Purpose, 1A, 1000V	DO41
1	5A/300Vac (T)	F1	F5464CT-ND	Littlefuse	FUSE 5A 300V, SlowBlow, Radial	8.50mm(L) x 4.00mm(W) x 8.00mm(H)
1	30mH	L1	Custom	Custom	30mH/0.5A	EI-11.6
2	6.8mH/0.5A	L2-3	Custom	Custom	6.8mH/0.5A, size: 8mm*10mm	8mmx10mm
2	320VAC	MOV1-2	V10E300P	LittelFuse	VARISTR 300VRMS 2500A 10MM STRGT	10 mm
1	4A, 800V	Q1	SPD04N80C3	ST	MOSFET, N-ch, 800V, 4A	DPAK
2	16.2K	R1 R16	Std	Std	Resistor, Chip, 1/4 watt, ± 5%	1206
1	1.1K	R13	Std	Std	Resistor, Chip, 1/4 watt, ± 5%	805
1	1R	R14	Std	Std	Resistor, Chip, 1/4 watt, ± 1%	1206
1	DNP	R15	Std	Std	Resistor, Chip, 1/4 watt, ± 1%	805
1	68K 1W	R2	Std	Std	Resistor, Leaded,1/watt, ± 5%	Leaded 1W
1	150k	R4	Std	Std	Resistor, Leaded, 1/2 watt, ± 5%	Leaded 0.5W
1	150k	R5	Std	Std	Resistor, Chip, 1/4 watt, ± 5%	1206
1	0R	R12	Std	Std	Resistor, Chip, 1/4 watt, ± 5%	805
1	15E	R6	Std	Std	Resistor, Chip, 1/4 watt, ± 5%	1206
1	68k	R7	Std	Std	Resistor, Chip, 1/4 watt, ± 1%	1206
1	11k	R8	Std	Std	Resistor, Chip, 1/4 watt, ± 1%	1206
1	6.8k	R9	Std	Std	Resistor, Chip, 1/4 watt, ± 5%	1206
2	DNP	R10 R11	Std	Std	Resistor, Chip, 1/4 watt, ± 5%	805
2	DNP	R3 R20	Std	Std	Resistor, Chip, 1/4 watt, ± 5%	805
2	DNP	R17 R19	Std	Std	Resistor, Chip, 1/4 watt, ± 5%	805

1	DNP	R18	Std	Std	Resistor, Leaded, 1/2 watt, ± 5%	Leaded 0.5W
1	EDR3909	T1	EDR3909 10 Pin Horizontal	Custom	1.2mH CF139 core or equivalent	Custom
1	TPS92314A	U1	TPS92314A	TI	Off-Line Primary Side Sensing Controller with PFC	SOIC-8
1	DNP	U2	TL431CDBZR	TI	Analog Precision Shunt Regulator	SOT-23-3

IMPORTANT NOTICE FOR TI REFERENCE DESIGNS

Texas Instruments Incorporated ("TI") reference designs are solely intended to assist designers (“Buyers”) who are developing systems that incorporate TI semiconductor products (also referred to herein as “components”). Buyer understands and agrees that Buyer remains responsible for using its independent analysis, evaluation and judgment in designing Buyer’s systems and products.

TI reference designs have been created using standard laboratory conditions and engineering practices. **TI has not conducted any testing other than that specifically described in the published documentation for a particular reference design.** TI may make corrections, enhancements, improvements and other changes to its reference designs.

Buyers are authorized to use TI reference designs with the TI component(s) identified in each particular reference design and to modify the reference design in the development of their end products. HOWEVER, NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY THIRD PARTY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT, IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI REFERENCE DESIGNS ARE PROVIDED "AS IS". TI MAKES NO WARRANTIES OR REPRESENTATIONS WITH REGARD TO THE REFERENCE DESIGNS OR USE OF THE REFERENCE DESIGNS, EXPRESS, IMPLIED OR STATUTORY, INCLUDING ACCURACY OR COMPLETENESS. TI DISCLAIMS ANY WARRANTY OF TITLE AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, QUIET ENJOYMENT, QUIET POSSESSION, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS WITH REGARD TO TI REFERENCE DESIGNS OR USE THEREOF. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY BUYERS AGAINST ANY THIRD PARTY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON A COMBINATION OF COMPONENTS PROVIDED IN A TI REFERENCE DESIGN. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, SPECIAL, INCIDENTAL, CONSEQUENTIAL OR INDIRECT DAMAGES, HOWEVER CAUSED, ON ANY THEORY OF LIABILITY AND WHETHER OR NOT TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES, ARISING IN ANY WAY OUT OF TI REFERENCE DESIGNS OR BUYER’S USE OF TI REFERENCE DESIGNS.

TI reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques for TI components are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

Reproduction of significant portions of TI information in TI data books, data sheets or reference designs is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards that anticipate dangerous failures, monitor failures and their consequences, lessen the likelihood of dangerous failures and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in Buyer’s safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed an agreement specifically governing such use.

Only those TI components that TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components that have ***not*** been so designated is solely at Buyer's risk, and Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265